Student Poster & Networking Session

Application Link: **Click Here**

Application Deadline: **February 16, 2026**

We encourage all students who have a submitted draft paper, and are the primary author of the paper, to apply to participate at the **Student Poster and Networking Session**. This special event provides additional opportunities to present your work and network with attendees from industry and academia.

Students who apply will be competitively selected for **Travel Grants** to attend the conference in Orlando, Florida.

Outstanding posters will be selected for **Conference Awards** based on technical merit, clarity and self-sufficiency of the content, novelty and originality of the work, overall impact of the poster display, and oral presentation at the session. A list of past winners can be found at: **https://www.ieee-itherm.net/prior-student-award-winners/**

》》》 **Apply Today!** 《《《

Applications opens:	Jan. 26
Applications deadline:	Feb. 16
Acceptance Notice:	Mar. 2
E-Poster Deadline:	Mar. 23
Poster Session:	May 28

For further information please contact:
Poster Chair: Dr. Aakrati Jain <aakrati.jain@ibm.com>
Poster Co-Chair: Dr. Kalind Baraya <kalind@ibm.com>

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